

TC1027/JC

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Class	Subclass
ISSUE CLASSIFICATION	

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PATENT NUMBER

U.S. UTILITY Patent Application

KW O.I.P.E.
SCANNED 117-3 Q.A. Am

PATENT DATE

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/837007		257		2827	Mitchell
APPLICANTS Mou-Shiung Lin Ming-Ta Lin Chuen-Jye Lin					
TITLE Structure and manufacturing method of a chip scale package					
PTO-2040 12/99					

ISSUING CLASSIFICATION

ORIGINAL		CROSS REFERENCE(S)	
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER ROW)
INTERNATIONAL CLASSIFICATION			
Continued on Issue Slip in Part 51, above			

FINAL DISCLAIMER	DRAWINGS			CLAIMS ATTACHED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Prior Claims & C.G.
The term of this patent is subsequent to (date)				NOTICE OF ALLOWANCE MAILED	
to extend beyond the expiration date of U.S. Patent No. (date)				ISSUE DATE	
The term of this patent shall not extend beyond the expiration date of U.S. Patent No. (date)				Attitude Due	Date Paid
The term of this patent has not been extended				ISSUE BATCH NUMBER	

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